

Title (en)
Electronic assembly and method of manufacturing same

Title (de)
Elektronische Anordnung und Verfahren zur Herstellung davon

Title (fr)
Ensemble électrique et son procédé de fabrication

Publication
EP 2840667 B1 20180516 (EN)

Application
EP 14192549 A 20081218

Priority
• US 839307 P 20071220
• EP 08867449 A 20081218

Abstract (en)
[origin: WO2009085975A2] An electronic assembly comprises a housing, a cover for the housing, a printed circuit board receivable in the housing, and a compliant pin header assembly. The compliant pin header assembly is moimtabie in the housing by inter-engaging features on the header assembly and the housing. The compliant pin header assembly has compliant pins for engaging corresponding features on the printed circuit board to connect the compliant pin header assembly electrically to the printed circ?ii board. The cover, when the electronic assembly is assembled, engages the housing and also engages the printed circuit board at a location spaced from an outer periphery of the printed circuit board.

IPC 8 full level
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CPC (source: CN EP US)
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Citation (examination)
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